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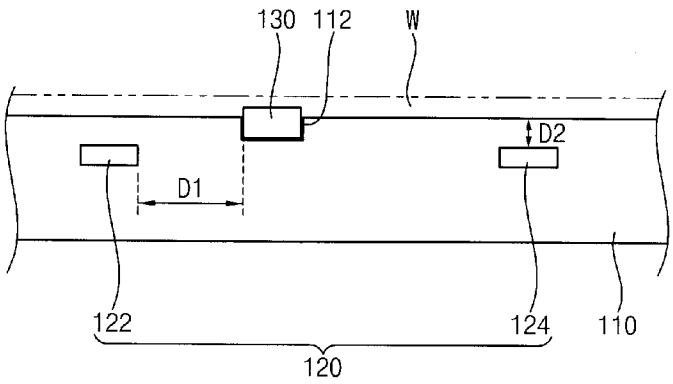
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(54) Title: APPARATUS FOR TRANSFERRING A WAFER

[Fig. 2]



(57) Abstract: An apparatus for transferring a wafer includes a ceramic blade, an electrode, a plurality of pads, a coating layer and a robot arm. The blade supports the wafer, and the electrode is disposed inside the blade. Electric power is applied to the electrode to generate an electrostatic force for holding the wafer. The pads are disposed on an upper surface of the blade, and thus frictional forces may be provided between the wafer and the pads. The coating layer is disposed on the blade. The robot arm is connected with the blade to move the blade.

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